

# SLVU2.8-4

# Ultraslow Capacitance Transient Voltage Suppressors Array Revision: A

### **General Description**

The SLVU2.8-4 is in an SOP-8 package and may be used to protect two high-speed line pairs. The "flow-thru" design minimizes trace inductance and reduces voltage overshoot associated with ESD events. The low clamping voltage of the SLVU2.8-4 minimizes the stress on the protected IC.

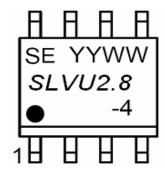
### **Applications**

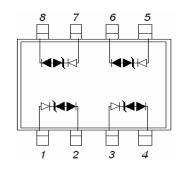
- Ethernet 10/100/1000 Base T
- WAN/LAN Equipment
- Desktops, Servers, Notebooks & Handhelds, base stations Laser Diode Protection

#### **Features**

- 400 W Peak Pulse Power per Line (tp=8/20μs)
- Protects two line pairs(four lines).
- Low capacitance
- Low Leakage Current.
- Low Operating and Clamping Voltages.
- Transient Protection for High Speed Data Lines to

IEC61000-4-2(ESD)±15kV(air),±8kV(Contact)
IEC61000-4-4(EFT) 40A(5/50ns)
IEC61000-4-5(lightning) 24A(8/20us)





### **Absolute Maximum Ratings**

Parameter	Symbol	Value	Units			
Peak Pulse Power (tp = 8/20µs) - See Fig1.	P <sub>PK</sub>	400	W			
Peak Pulse Current (tp = 8/20µs)	I <sub>PP</sub>	24	Α			
Storage Temperature Range	T <sub>STG</sub>	-55 to 150	°C			
Operating Junction Temperature Range	TJ	-55 to 150	°C			

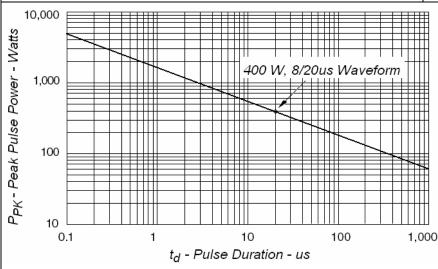


Fig1. Peak Pulse Power VS Pulse Time

# **Electrical Parameter**

Symbol	Parameter		
I <sub>PP</sub>	Peak Pulse Current		
V <sub>C</sub>	Clamping Voltage @ I <sub>PP</sub>		
$V_{RWM}$	Reverse Stand-Off Voltage		
I <sub>R</sub>	Reverse Leakage Current @ V <sub>RWM</sub>		
$V_{SB}$	Snap-Back Voltage @ I <sub>SB</sub>		
I <sub>SB</sub>	Snap-Back Current		
$V_{PT}$	Punch-Through Voltage		
I <sub>PT</sub>	Punch-Through Current		
$V_{BRR}$	Reverse Breakdown Voltage @ I <sub>BRR</sub>		
I <sub>BRR</sub>	Reverse Breakdown Current		

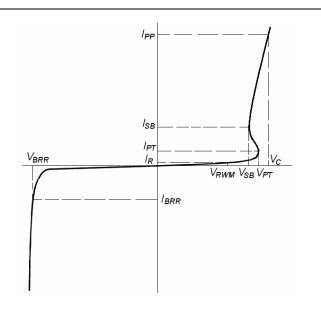
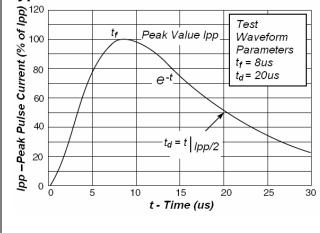


Fig2. SLVU2.8-4 IV Characteristic Curve

# **Electrical Characteristics**

Parameter	Symbol	Conditions	Minimum	Typical	Maximum	Units
Reverse Stand-Off Voltage	$V_{RWM}$				2.8	V
Punch-Through Voltage	$V_{PT}$	I <sub>PT</sub> = 2uA 3.0				V
Snap-Back Voltage	$V_{SB}$	I <sub>SB</sub> = 50mA 2.8				V
Reverse Leakage Current	I <sub>R</sub>	V <sub>RWM</sub> =2.8V, T=25℃			1	uA
		(Each Line)			Į.	
Clamping Voltage	V <sub>C</sub>	$I_{PP}$ =2A, $t_{P}$ =8/20us			5.5	V
		(Each Line)				
Clamping Voltage	V <sub>C</sub>	$I_{PP}$ =5A, $t_{P}$ =8/20us			8.5	V
		(Each Line)		0.5		V
Clamping Voltage	V <sub>C</sub>	$I_{PP}$ =24A, $t_{P}$ =8/20us		15		V
		(Each Line)			10	\ \ \
Junction Capacitance	C <sub>j</sub>	VR =0V, f =1MHz	2.5		5	pF
		(Each Line)		3.5		

# **Typical Characteristics**



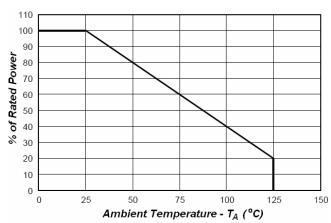
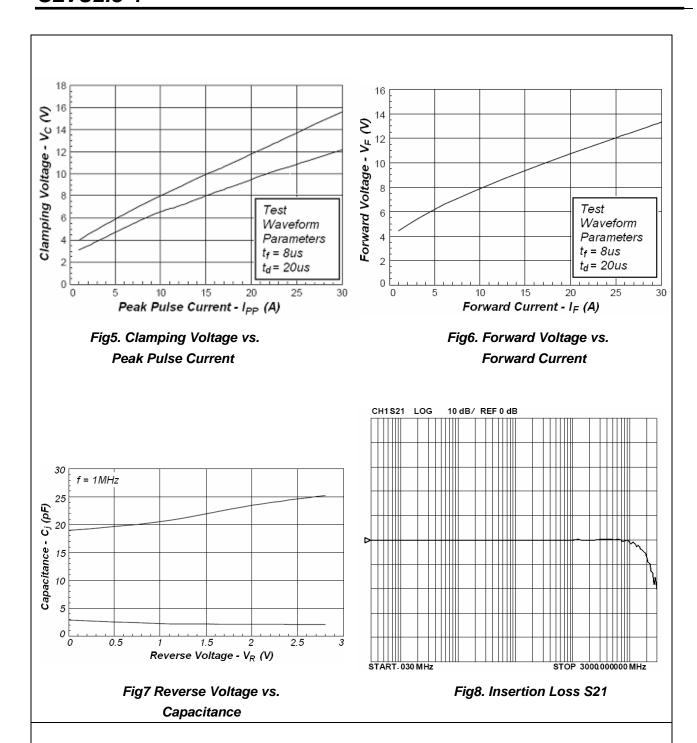


Fig3. Pulse Waveform

Fig4. Power Derating Curve



### **Application Note**

Electronic equipment is susceptible to damage caused by Electrostatic Discharge (ESD), Electrical Fast Transients (EFT), and tertiary lightning effects. Knowing that equipment can be damaged, the SLVU2.8-4 was designed to provide the level of protection required to safe guard sensitive equipment. This product can be used in different configurations to provide a level of protection to meet unidirectional line requirements as well as bidirectional requirements either in a common-mode or differential-mode configuration.

#### **Unidirectional Common-Mode Protection (Figure 9)**

The SLVU2.8-4 provides up to four lines of protection in a common-mode configuration as depicted in figure 9. Circuit connectivity is as follows:

- Line 1 is connected to Pin 1
- Line 2 is connected to Pin 7
- Line 3 is connected to Pin 3
- Line 4 is connected to Pin 5
- Pins 2, 4, 7 and 8 are connected to ground

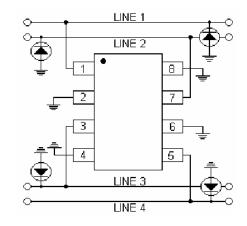
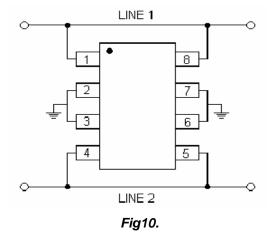


Fig9.

### Bidirectional Common-Mode Protection (Figure 10)

The SLVU2.8-4 provides up to two lines of protection in a common-mode configuration as depicted in figure 10. Circuit connectivity is as follows:

- Line 1 is connected to Pins 1 & 8
- Line 2 is connected to Pins 4 & 5
- Pins 2, 3, 6, and 7 are connected to ground



### Bidirectional different-Mode Protection (Figure 11)

The SLVU2.8-4 provides up to two-line pairs of protection in a differential-mode configuration as depicted in figure 11.

Circuit connectivity is as follows:

- Line Pair 1 is connected to Pins 1 & 2
- Line Pair 1 is connected to Pins 7 & 8
- Line Pair 2 is connected to Pins 3 & 4
- Line Pair 2 is connected to Pins 5 & 6

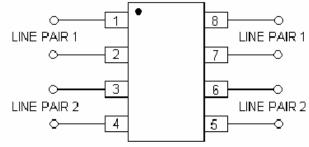
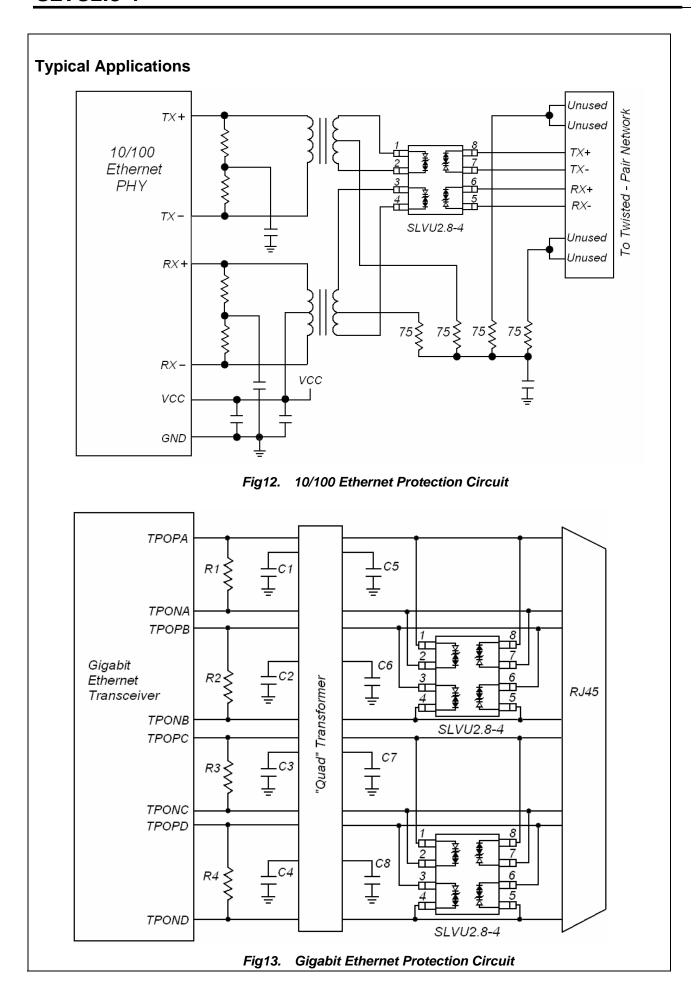


Fig11.

#### Circuit Board Layout Protection

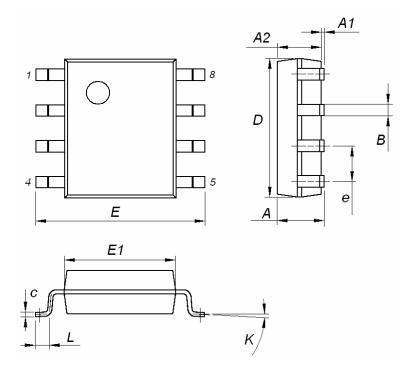
Circuit board layout is critical for Electromagnetic Compatibility (EMC) protection. The following guidelines are recommended:

- The protection device should be placed near the input terminals or connectors, the device will divert the transient current immediately before it can be coupled into the nearby traces.
- The path length between the TVS device and the protected line should be minimized.
- All conductive loops including power and ground loops should be minimized.
- The transient current return path to ground should be kept as short as possible to reduce parasitic inductance
- Ground planes should be used whenever possible. For multilayer PCBs, use ground vias.



## **SOP-8 Mechanical Data**

Dim	Millimeters			
	Min	TYP	Max	
Α			1.75	
A1	0.10		0.25	
A2	1.35	1.55	1.75	
В	0.35	0.42	0.49	
С	0.19		0.25	
D	4.80	4.90	5.00	
E	5.80	6.00	6.20	
E1	3.80	3.95	4.00	
е		1.27		
L	0.40		0.90	
K	0°		8°	



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## SHANGHAI SINO-IC MICROELECTRONICS CO., LTD

Add: No.55-302, 200 SongTao Road, ZhangJiang Hi-Tech Park, Pudong, Shanghai 201203, China

**Phone:** +86-21-50275099 50805407 50805408

Fax: +86-21-50275077

Email: webmaster@sino-ic.com
Website: http://www.sino-ic.com